



General Description

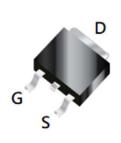
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

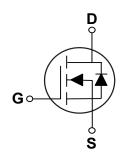
BV _{DSS}	R _{DS(ON)}	Ι _D
40 V	6.6 mΩ	75 A

Features

- $R_{DS(ON)} \leq 6.6 m\Omega @V_{GS} = 10V$
- · Improved dv/dt Capability
- Fast Switching
- · Green Device Available

TO-252 Pin Configuration





Applications

- · Power Management Switches
- DC/DC Converter

Absolute Maximum Ratings T _c =25°C unless otherwise noted						
Symbol	bol Parameter Rating					
V_{DS}	Drain-Source Voltage	40	V			
V_{GS}	Gate-Source Voltage	±20	V			
I _D	Drain Current - Continuous (T _C =25°C)	75	Α			
I _{DM}	Drain Current - Pulsed (NOTE 1)	161	Α			
E _{AS}	Single Pulse Avalanche Energy (NOTE 2)	88	mJ			
I _{AS}	Single Pulse Avalanche Current (NOTE 2)	42	Α			
P _D	Power Dissipation (T _C =25°C)	44.6	W			
T_J	Operating Junction Temperature Range	-55 to 150	°C			
T _{STG}	Storage Temperature Range	-55 to 150	°C			
Marking Code		ND6P6				

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	75	°C/W		
$R_{ heta JC}$	Thermal Resistance Junction to Case	2.8	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =40V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	IStatic Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			6.6	- mΩ
		V _{GS} =4.5V , I _D =10A			8.8	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.0		2.5	V
gfs	Forward Transconductance	V_{DS} =5V , I_{D} =5A		28		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			20.5		
Q_{gs}	Gate-Source Charge	V_{DD} =20V , V_{GS} =4.5V , I_{D} =10A		5.9		nC
Q_{gd}	Gate-Drain Charge			9.7		
$T_{d(on)}$	Turn-On Delay Time			15.4		
T_r	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω ,		9		nS
$T_{d(off)}$	Turn-Off Delay Time	I _D =1A		76		110
T_f	Fall Time			7.1		
C _{iss}	Input Capacitance			3310		
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		280		pF
C _{rss}	Reverse Transfer Capacitance			209		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V , Force Current			75	Α
V_{SD}	Diode Forward Voltage	V_{GS} =0V , I_{S} =1A			1	V

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =42A.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.





Characteristics Curves

FIG. 1-Output Characteristics

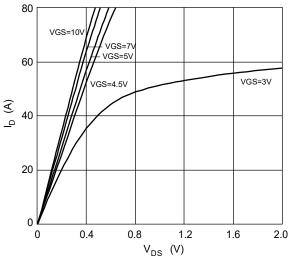


FIG. 3-Normalized $R_{DS(ON)}$ vs. I_D

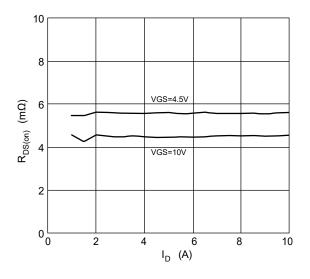


FIG. 5-Safe Operating Area

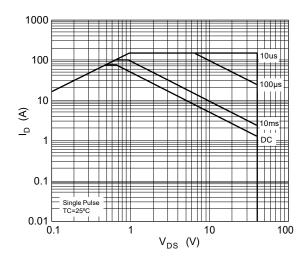


FIG. 2-Transfer Characteristics

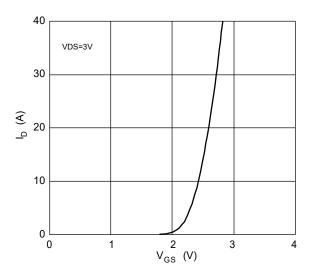


FIG. 4-Gate Charge Characteristics

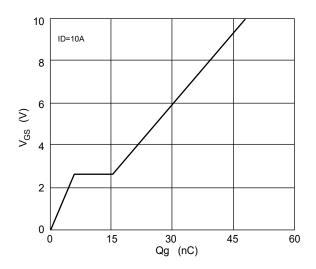
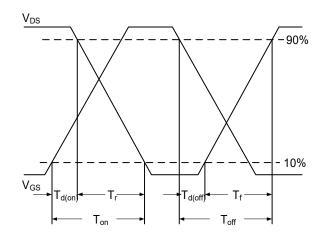


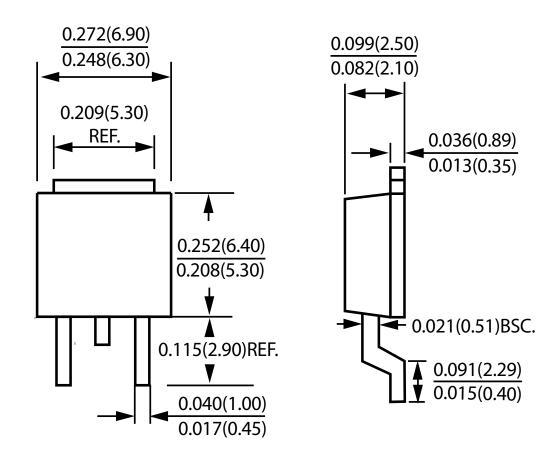
FIG. 6-Switching Time Waveform







Package Outline Dimensions



TO-252Dimensions in inches and (millimeters)





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